

VF-8 Via Fill System

Model VF-8



The Credence VF8F Via Filling System is a proven concept for reliable via filling for both HTCC and LTCC materials. The unique design of the VF8F provides quick setup between tape layers. The drop-in tooling reservoir is loaded with via filling paste and covered with a pre-punched mask that was produced on the same via-punch machine that punched the tapes to be filled. The mask is located using the same locating holes that locate the framed tape providing perfect alignment automatically.

The tape is loaded onto the mask and a piece of porous paper is placed on top of the tape to allow the air in the vias to escape as the vias are filled. The tool is shuttled into the press and an upper clamp pulls the tooling up against the top platen. The Ram then actuates, pressing upward against the bottom of the tool to extrude via paste through the holes in the mask into the vias in the tape. The process times out and then the tool is released and shuttled out to the load position. The top paper is discarded and the filled tape is lifted off of the mask. The tape is then inspected using the back-light and microscope.

Specifications and Components

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| <ul style="list-style-type: none"> • Utilizes punched masks from via punching process. • Tooling available for 6"x6", 8"x8" framed tapes. One tool included. • Unique piston reservoir design allows for easy cleanup and setup. • Dual Action extrusion process | <ul style="list-style-type: none"> • Filling Pressure up to 3000 lbs. • Interlocked motions • 2-hand no-tie-down Cycle Safety Controls • PLC Controller with Cycle Time and Pressure as Inputs • 110/240V Single Phase, 50/60 HZ • Backlight inspection station built in. |
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Included

- Tooling supplied for 6" framed tape
- Tooling supplied for 8" framed tape
- 4 magazines

Options (Consult Factory)

- Microscope inspection station